

Amendments to the Claims:

The listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1-2. (Canceled)

3. (Currently Amended) A method for fabricating a nonradiative dielectric waveguide, comprising the steps of:

forming a first conductive film on a semiconductor substrate;

forming a dielectric film on said first conductive film ~~a second dielectric film whose dielectric constant is larger than that of a first dielectric film;~~

etching said ~~second~~ dielectric film to form a transmission line;

embedding a first sacrificial layer in an area where said dielectric film has been etched away;

forming a second sacrificial layer on said dielectric film and said first sacrificial layer;

etching away said second sacrificial layer everywhere except a plurality of portions thereof;

embedding ~~said first dielectric film~~ a second conductive film in an area where said second ~~dielectric film~~ sacrificial layer has been etched away; and

~~forming a second conductive film on said first dielectric film and said second dielectric film to form a nonradiative dielectric waveguide~~

removing said first and second sacrificial layers by etching away said first and second sacrificial layers.

4. (Currently Amended) A method for fabricating a nonradiative dielectric waveguide as claimed in claim 3, wherein ~~said substrate includes a~~ Micro-Electro-Mechanical System (MEMS) circuit is formed in said substrate prior to forming said first conductive film ~~previously formed therein.~~

5. (Withdrawn) A method for fabricating a nonradiative dielectric waveguide, comprising the steps of: forming a conductive film on a substrate; forming a first sacrificial film on said conductive film; forming a groove for a transmission line passing through said first sacrificial film; embedding a dielectric into said groove formed passing through said first sacrificial film; forming a second sacrificial layer on said first sacrificial layer into which said dielectric has been embedded, and etching away said second sacrificial layer everywhere except a plurality of portions thereof; forming a conductive film in an area where said second sacrificial layer has been etched away; and etching away said first and second sacrificial layers.

6. (Withdrawn) A method for fabricating a nonradiative dielectric waveguide as claimed in claim 5, wherein a MEMS circuit is fabricated into said substrate.

7. (Withdrawn) A method for fabricating a nonradiative dielectric waveguide, comprising the steps of: forming a first dielectric film on a substrate; forming a groove for a transmission line to such a depth that does not pass through said first dielectric film; embedding a second dielectric, whose dielectric constant is larger than that of said first dielectric film, into said groove formed in said first dielectric film; forming another first dielectric film on said first dielectric film and said second dielectric film; forming two grooves one spaced apart from the other by a distance smaller than the width of said second dielectric, said grooves being formed down to said substrate in such a manner as to cut off both edges of said second dielectric; and embedding a conductor into each of said two grooves.

8. (Withdrawn) A method for fabricating a nonradiative dielectric waveguide as claimed in claim 7, wherein a MEMS circuit is fabricated into said substrate.

9-12. (Canceled)